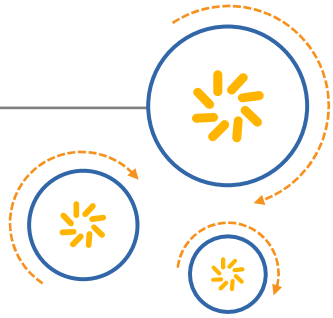
RF360 Europe GmbH

A Qualcomm – TDK Joint Venture



SAW components

SAW duplexer

LTE band 71

Series/type:	B1237
Ordering code:	B39661-B1237-L210
Date:	April 20, 2018
Version:	1.1

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RF360 Europe GmbH, Anzinger Str. 13, München, Germany

SAW components **B1237**

SAW duplexer **634.5 / 680.5 MHz**

Preliminary data sheet

Table of contents

Preliminary data sheet

1 Application

- Duplexer for LTE band 71

2 Features

- Package size 2.5±0.1 mm × 2.0±0.1 mm
- Package height 0.7 mm (max.)
- Approximate weight 9 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

Figure 1: Picture of component with example of product marking.

3 Package

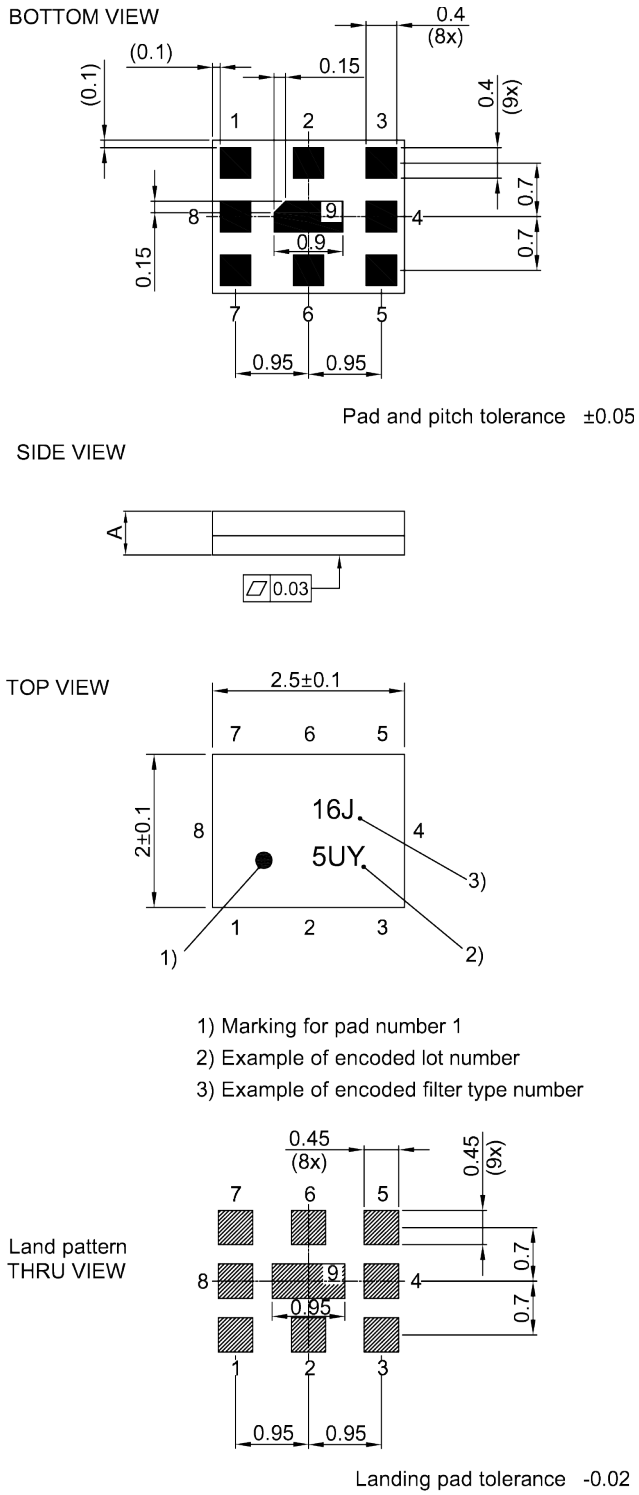

Figure 2: Drawing of package with package height A = 0.7 mm (max.). See Sec. Package information (p. 25).

4 Pin configuration

- 1 RX
- 3 TX
- 6 ANT
- 2, 4, 5, 7, 8, 9 Ground

5 Matching circuit

■ L_{p6} = 16 nH

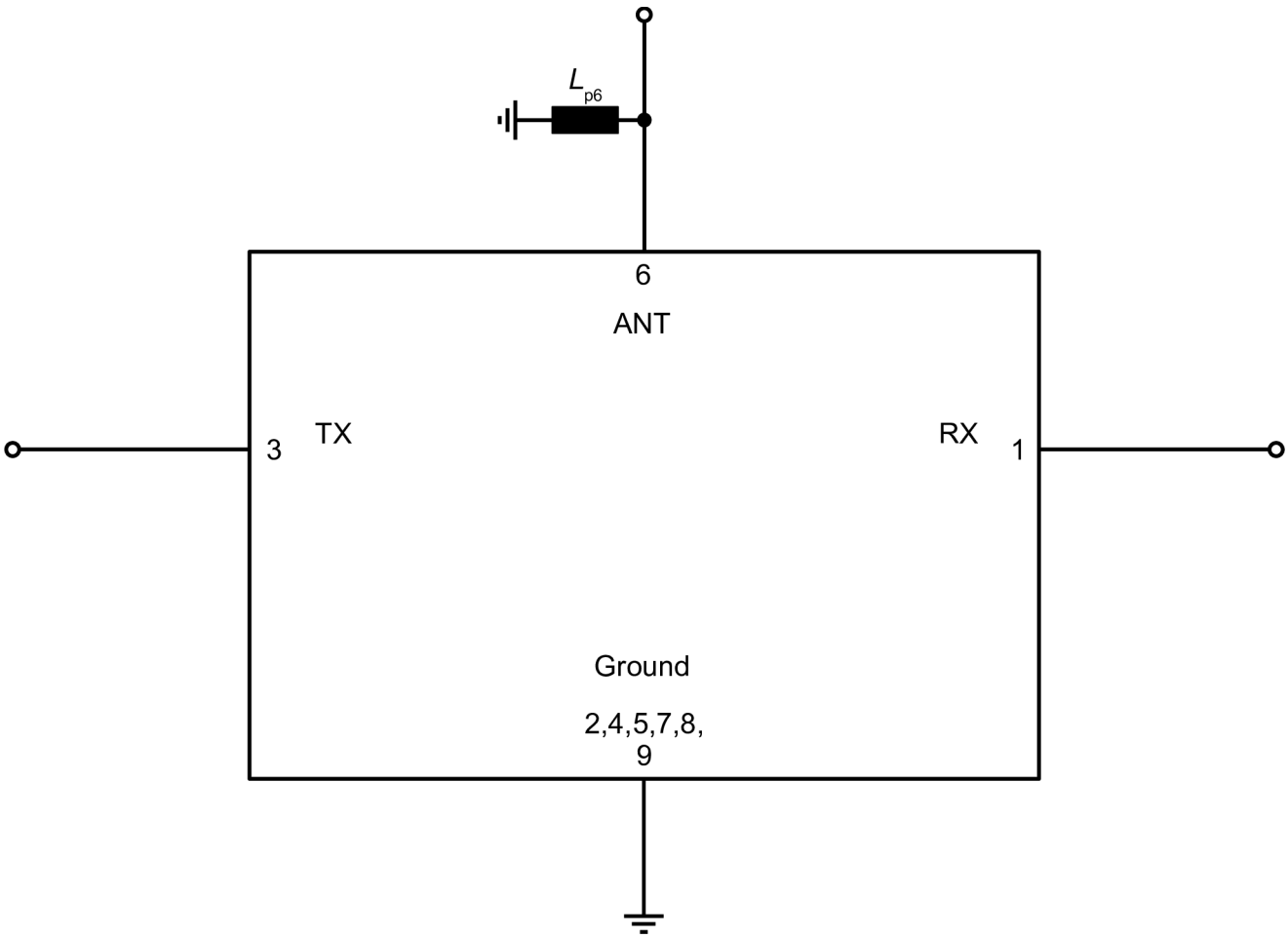

Figure 3: Schematic of matching circuit.

External shunt inductor for ESD protection is recommended at any ports towards antenna.

6 Characteristics

6.1 TX – ANT

Temperature range for specification	T_{SPEC}	= −30 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 16 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	680.5	—	MHz
Maximum insertion attenuation							
	663 ... 698	MHz	$\alpha_{INT,max}$ [2)]	—	1.5	2.2	dB
	663.34 ... 697.66	MHz	α_{max}	—	2.0	2.7[3)]	dB
	663.34 ... 697.66	MHz	α_{max}	—	2.0	3.0	dB
Amplitude ripple (p-p)			$\Delta\alpha$[4)]				
	663.34 ... 697.66	MHz		—	0.9	2.0	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	663.34 ... 697.66	MHz		—	1.2	2.0	
@ ANT port	663.34 ... 697.66	MHz		—	1.3	2.0	
Minimum attenuation			α_{min}				
	10 ... 608	MHz		30	47	—	dB
	608 ... 614	MHz		50	57	—	dB
	617.34 ... 651.66	MHz		48	60	—	dB
	717 ... 728	MHz		15	25	—	dB
	722 ... 729	MHz		10	43	—	dB
	729 ... 746	MHz		45	67	—	dB
	746 ... 768	MHz		45	52	—	dB
	768 ... 805	MHz		40	52	—	dB
	824 ... 849	MHz		30	36	—	dB
	859 ... 894	MHz		40	48	—	dB
	1164 ... 1250	MHz		40	52	—	dB
	1326 ... 1396	MHz		30	49	—	dB
	1559 ... 1563	MHz		45	69	—	dB
	1565.42 ... 1573.374	MHz		45	69	—	dB
	1573.374 ... 1577.644	MHz		45	70	—	dB
	1577.644 ... 1585.42	MHz		45	70	—	dB
	1597.551 ... 1605.886	MHz		45	70	—	dB
	1710 ... 1755	MHz		30	60	—	dB
	1805 ... 1880	MHz		30	56	—	dB
	1930 ... 1990	MHz		45	56	—	dB
	1989 ... 2094	MHz		45	56	—	dB
	2110 ... 2200	MHz		40	57	—	dB

Characteristics TX – ANT			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
	2400... 2484	MHz	35	53	—	dB
	2652... 2792	MHz	30	51	—	dB
	4900... 5950	MHz	15	27	—	dB

1) See Sec. Matching circuit (p. 6).
2) Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
3) Valid for typical temperature T = +25 °C.
4) Over any 5 MHz.

6.2 RX – ANT

Temperature range for specification T_{SPEC} = −30 °C ... +85 °C
TX terminating impedance Z_{TX} = 50 Ω
ANT terminating impedance Z_{ANT} = 50 Ω with par. 16 nH[1)]
RX terminating impedance Z_{RX} = 50 Ω

Characteristics RX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	634.5	—	MHz
Maximum insertion attenuation							
	617 ... 652	MHz	$\alpha_{INT,max}$ [2)]	—	1.6	2.3	dB
	617.34 ... 651.66	MHz	α_{max}	—	2.0	2.7[3)]	dB
	617.34 ... 651.66	MHz	α_{max}	—	2.0	3.3	dB
Amplitude ripple (p-p)			$\Delta\alpha$[4)]				
	617.34 ... 651.66	MHz		—	0.8	2.5	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	617.34 ... 651.66	MHz		—	1.5	2.0	
@ RX port	617.34 ... 651.66	MHz		—	1.5	2.0	
Average attenuation			α_{avg}				
	608 ... 612	MHz		3	8	—	dB
Minimum attenuation							
	1.0 ... 608	MHz	$\alpha_{INT,min}$ [5)]	13	35	—	dB
	35 ... 55	MHz	α_{min}	50	70	—	dB
	657.56 ... 662.44	MHz	$\alpha_{WLAN,min}$ [6)]	12	27	—	dB
	663.34 ... 697.66	MHz	α_{min}	45	56	—	dB
	709 ... 740	MHz	α_{min}	20	41	—	dB
	776 ... 793	MHz	α_{min}	35	39	—	dB
	793 ... 805	MHz	α_{min}	35	39	—	dB
	824 ... 849	MHz	α_{min}	35	40	—	dB
	1058 ... 1138	MHz	α_{min}	25	42	—	dB
	1163 ... 1204	MHz	α_{min}	35	41	—	dB
	1233 ... 1281	MHz	α_{min}	35	40	—	dB
	1461 ... 1484	MHz	α_{min}	35	56	—	dB
	1653 ... 1698	MHz	α_{min}	25	45	—	dB
	1710 ... 1755	MHz	α_{min}	40	45	—	dB
	1850 ... 1920	MHz	α_{min}	40	47	—	dB
	1851 ... 1956	MHz	α_{min}	40	47	—	dB
	2305 ... 2315	MHz	α_{min}	20	43	—	dB
	2327 ... 2407	MHz	α_{min}	20	43	—	dB
	2400 ... 2500	MHz	α_{min}	37	42	—	dB

Characteristics RX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
2468... 2608	MHz	α_{min}		20	42	—	dB
2922... 2967	MHz	α_{min}		20	40	—	dB
4037... 4162	MHz	α_{min}		20	29	—	dB
4317... 4472	MHz	α_{min}		15	22	—	dB
4900... 5950	MHz	α_{min}		10	18	—	dB

1) See Sec. Matching circuit (p. 6).
2) Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
3) Valid for typical temperature T = +25 °C.
4) Over any 5 MHz.
5) Integrated over 6 MHz.
6) Average over each WLAN channel with band width of 4.875 MHz.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= −30 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 16 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX			**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Minimum isolation	α_{min}					
	617.34 ... 651.66	MHz	55	62	—	dB
	663.34 ... 697.66	MHz	55[2)]	58	—	dB
	663.34 ... 697.66	MHz	50	58	—	dB
	1326 ... 1396	MHz	30	61	—	dB
	1989 ... 2094	MHz	30	57	—	dB
	2652 ... 2792	MHz	30	54	—	dB

1) See Sec. Matching circuit (p. 6).
2) Valid for temperature T = 0 °C...+85 °C.

7 Maximum ratings

Storage temperature	T_{STG} [2] = −40 °C ... +85 °C	
DC voltage	$\lvert V_{DC} \rvert$ [1] = 0 V (max.)	
ESD voltage		
	V_{ESD} [3] = 200 V (max.)	Machine model.
	V_{ESD} [4] = 500 V (max.)	Human body model.
	V_{ESD} [5] = 700 V (max.)	Charged device model.
Input power	P_{IN}	
@ TX port: 663.34 ... 697.66 MHz	t.b.d. dBm (max.)	5 MHz LTE uplink signal (25 RB) for 5000 h @ 85 °C.
@ TX port: other frequency ranges	10 dBm (max.)	Continuous wave for 5000 h @ 50 °C.

1) In case of applied DC voltage blocking capacitors are mandatory.
2) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
3) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.
4) According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.
5) According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

8 Transmission coefficients

8.1 TX – ANT

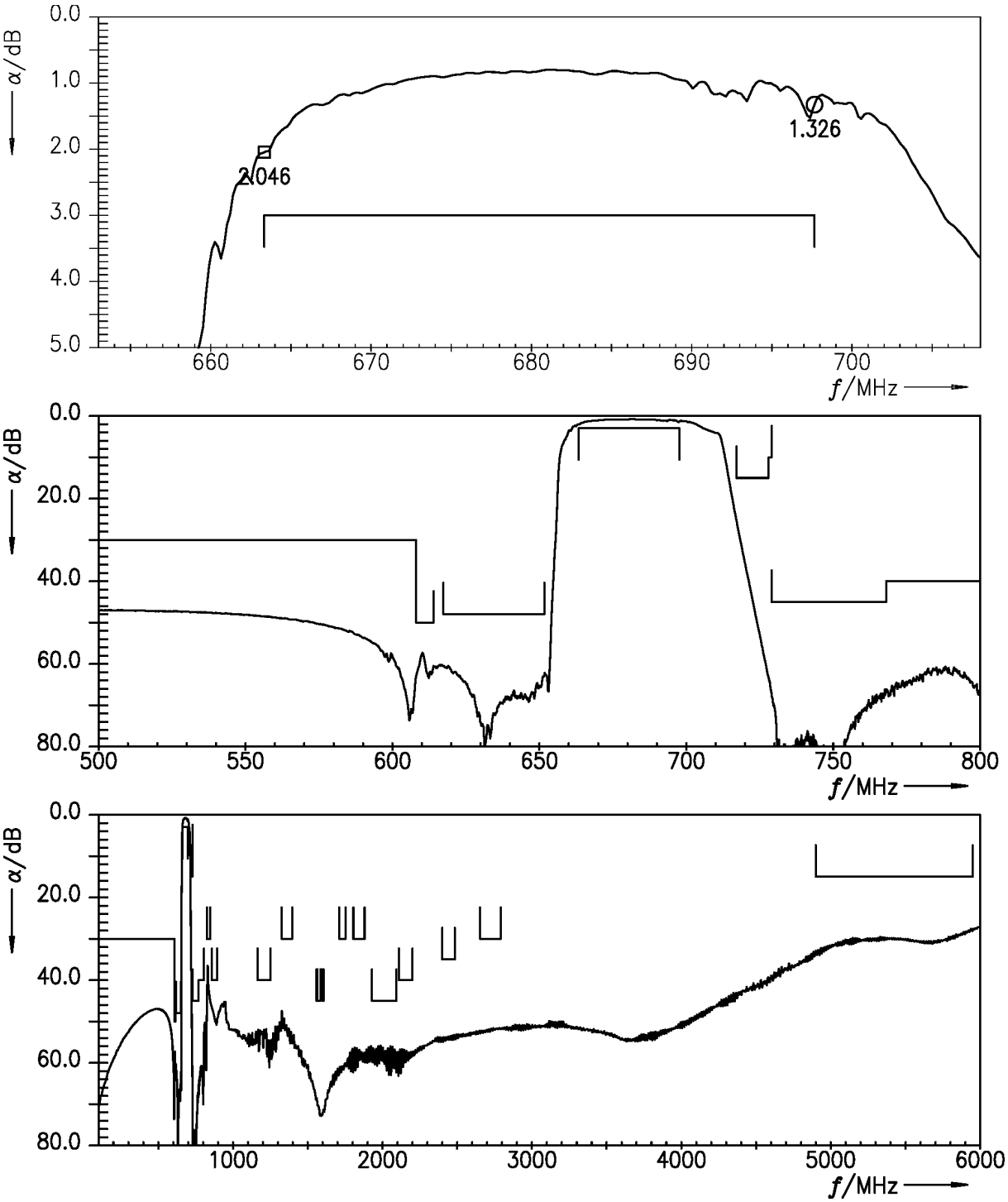

Figure 4: Attenuation TX – ANT.

8.2 RX – ANT

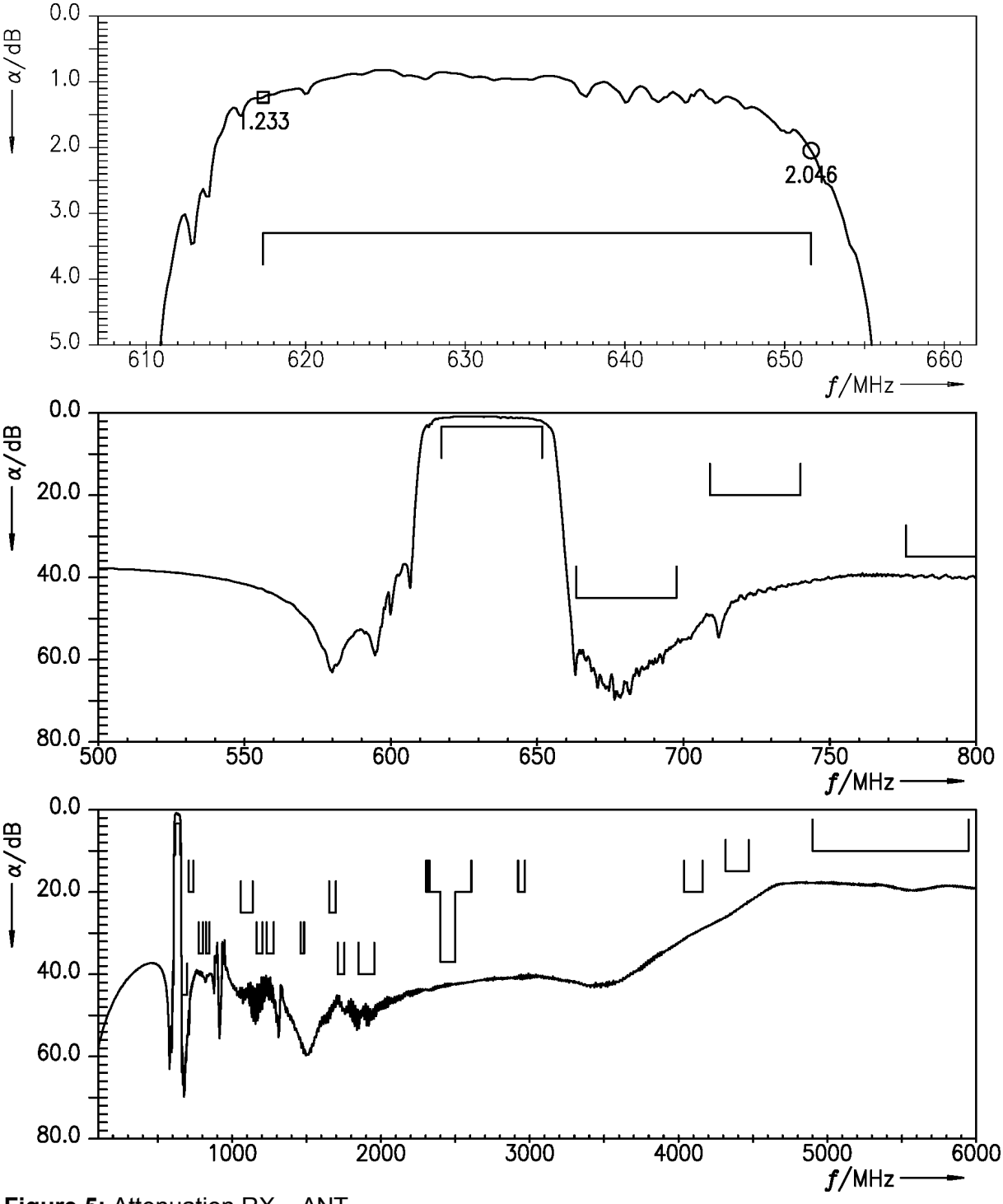

Figure 5: Attenuation RX – ANT.

8.3 TX – RX

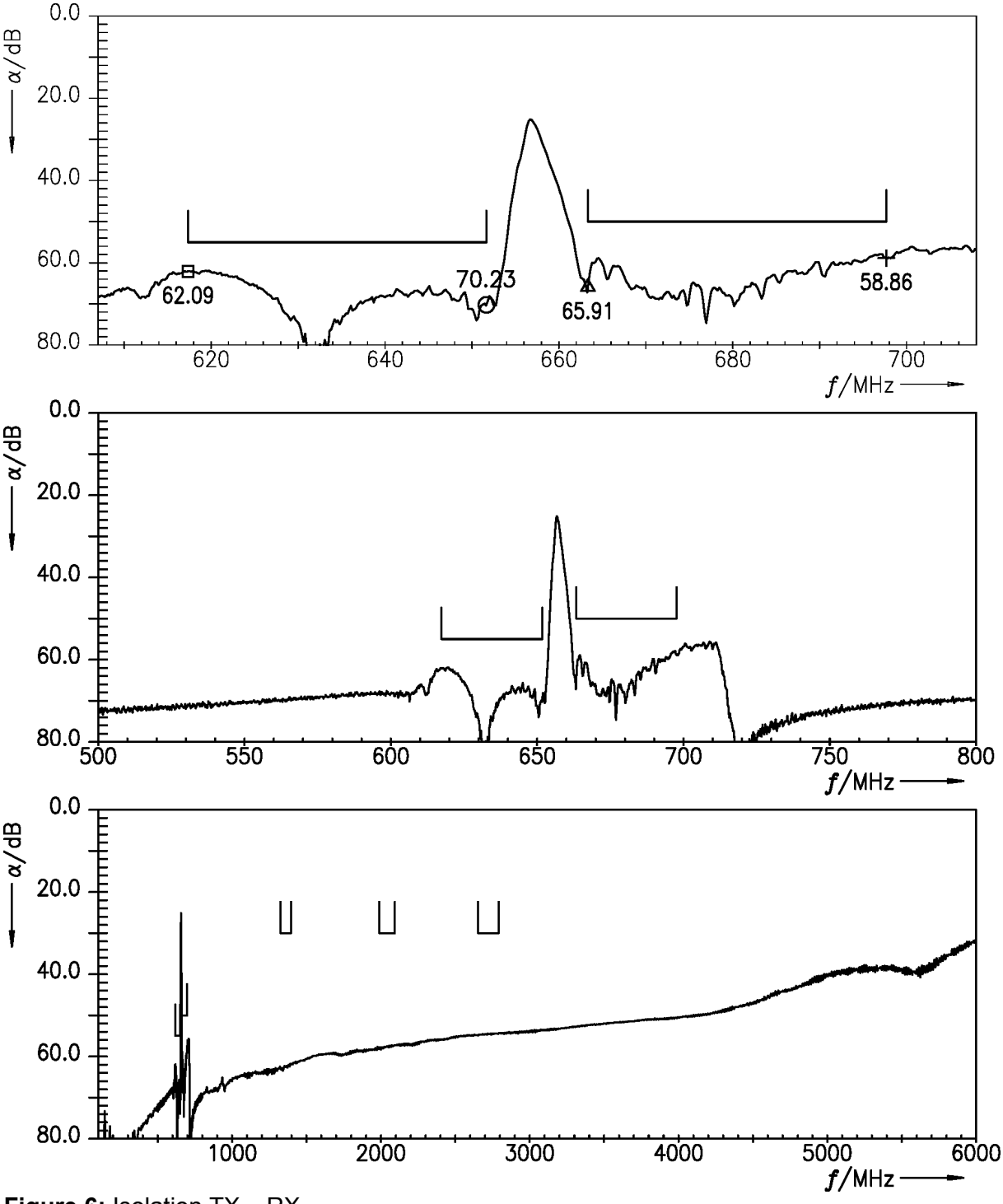

Figure 6: Isolation TX – RX.

9 Transmission coefficient (WLAN)

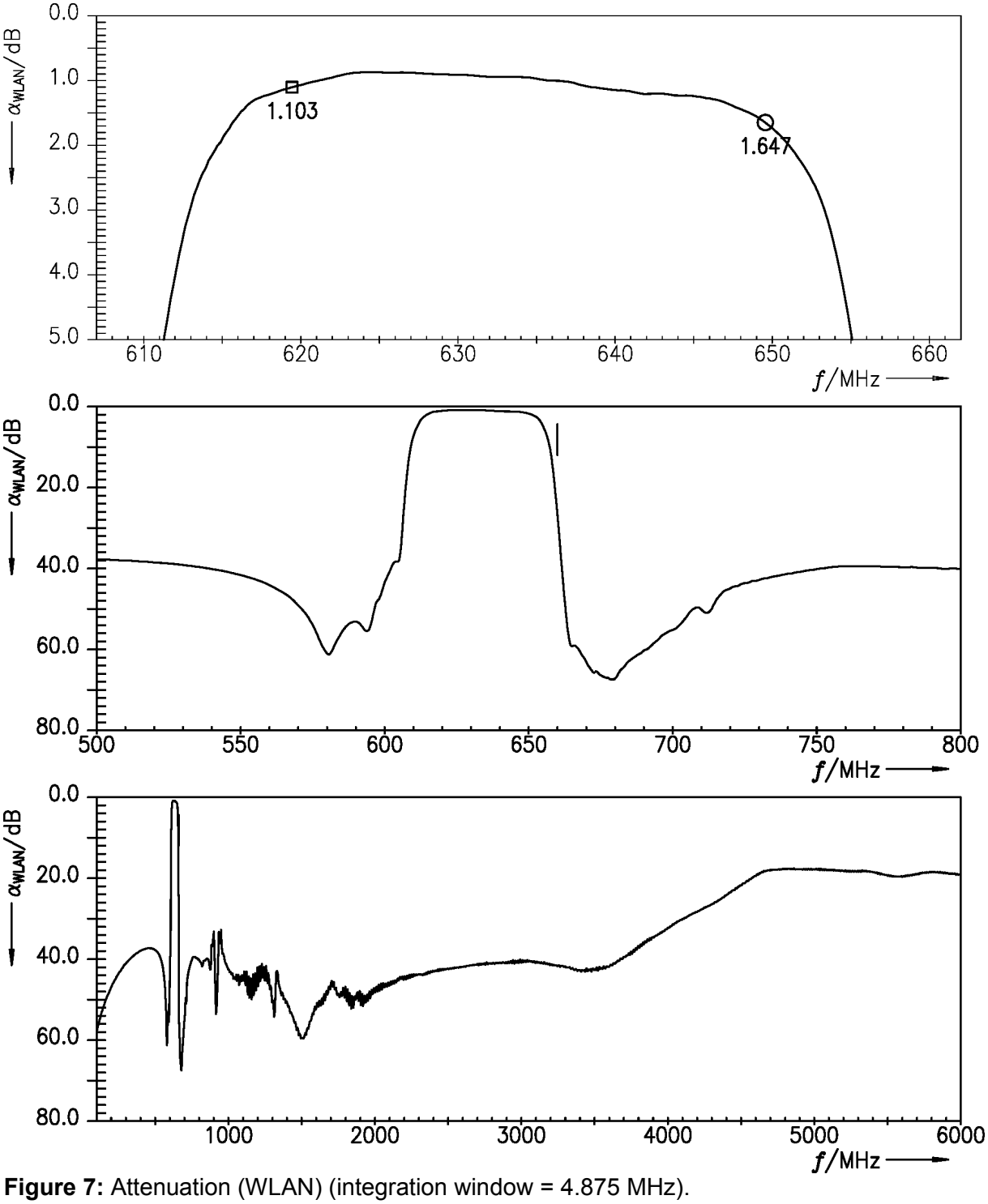

Figure 7: Attenuation (WLAN) (integration window = 4.875 MHz).

10 Reflection coefficients

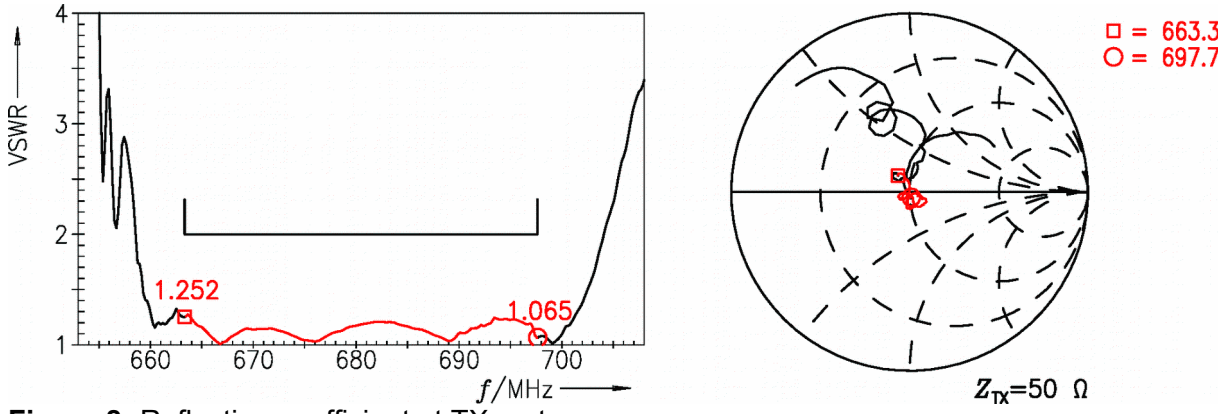

Figure 8: Reflection coefficient at TX port.

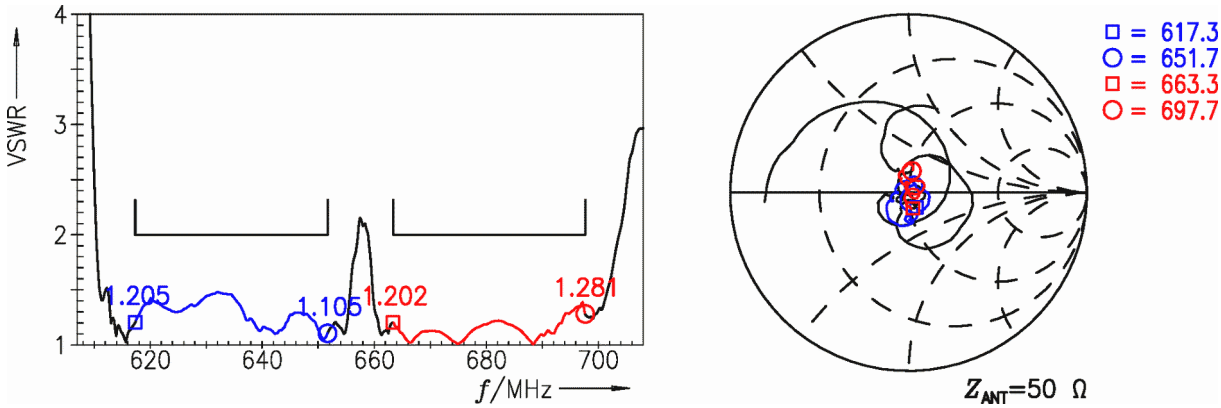

Figure 9: Reflection coefficient at ANT port.

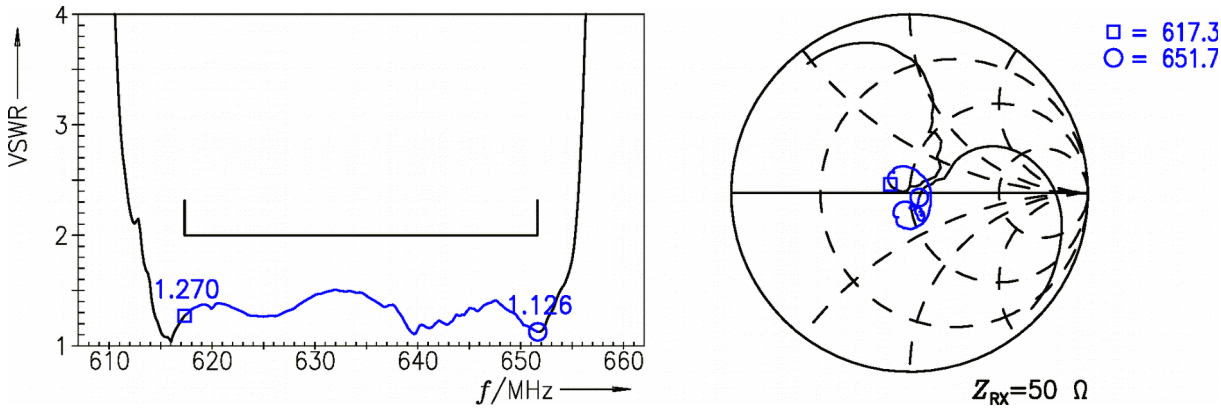

Figure 10: Reflection coefficient at RX port.

11 Packing material

11.1 Tape

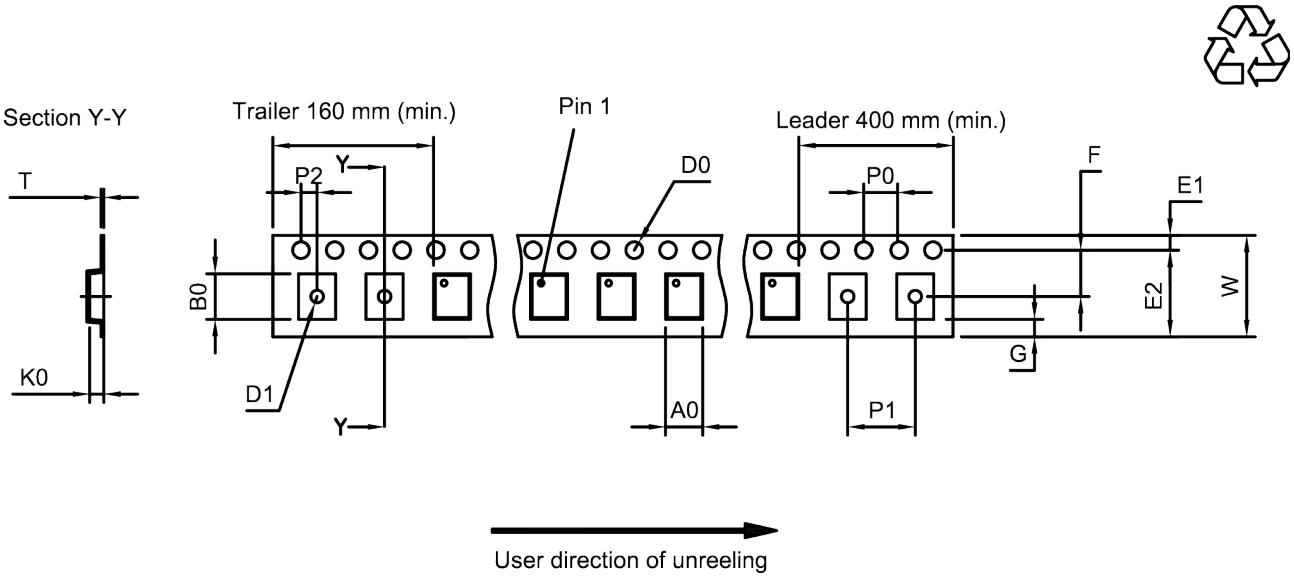

Figure 11: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A_0	2.3±0.05 mm
B_0	2.8±0.05 mm
D_0	1.5+0.1/−0 mm
D_1	1.0 mm (min.)
E_1	1.75±0.1 mm

E_2	6.25 mm (min.)
F	3.5±0.05 mm
G	0.75 mm (min.)
K_0	0.85±0.05 mm
P_0	4.0±0.1 mm

P_1	4.0±0.1 mm
P_2	2.0±0.05 mm
T	0.25±0.03 mm
W	8.0+0.3/−0.1 mm

Table 1: Tape dimensions.

11.2 Reel with diameter of 180 mm

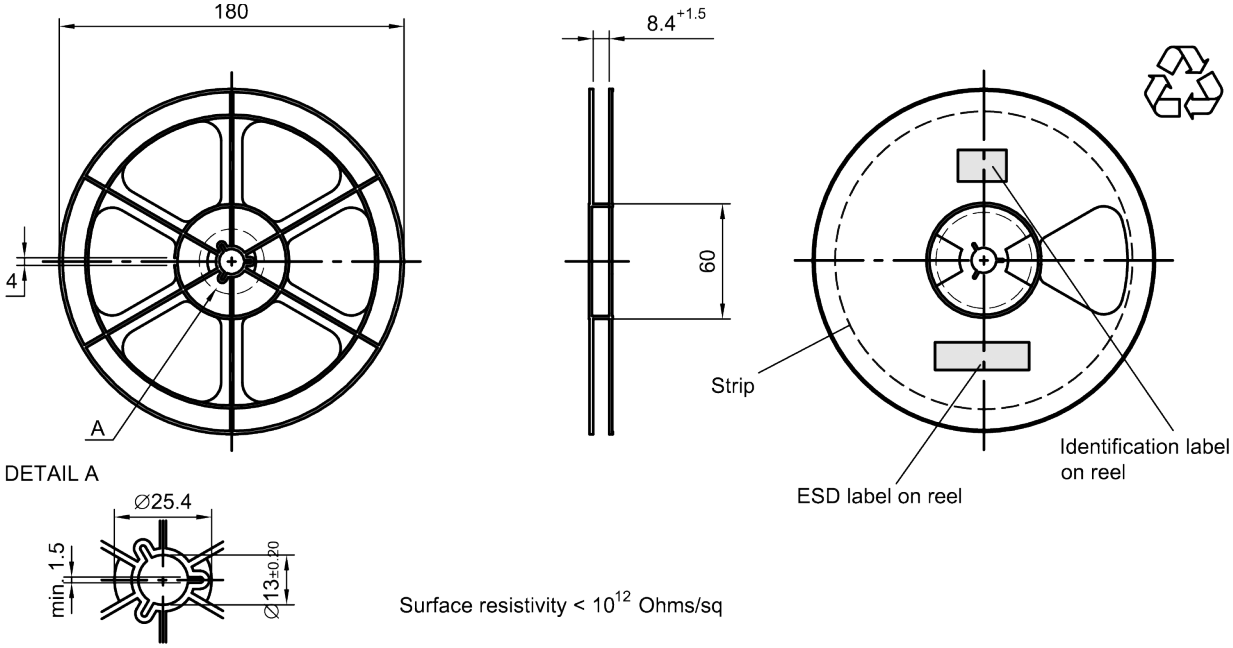

Figure 12: Drawing of reel (first-angle projection) with diameter of 180 mm.

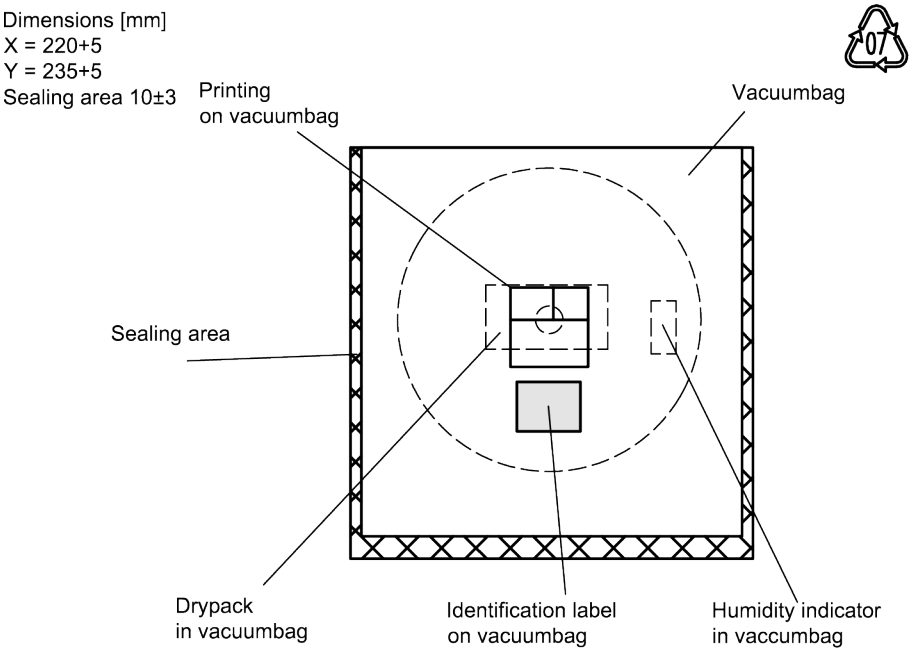

Figure 13: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

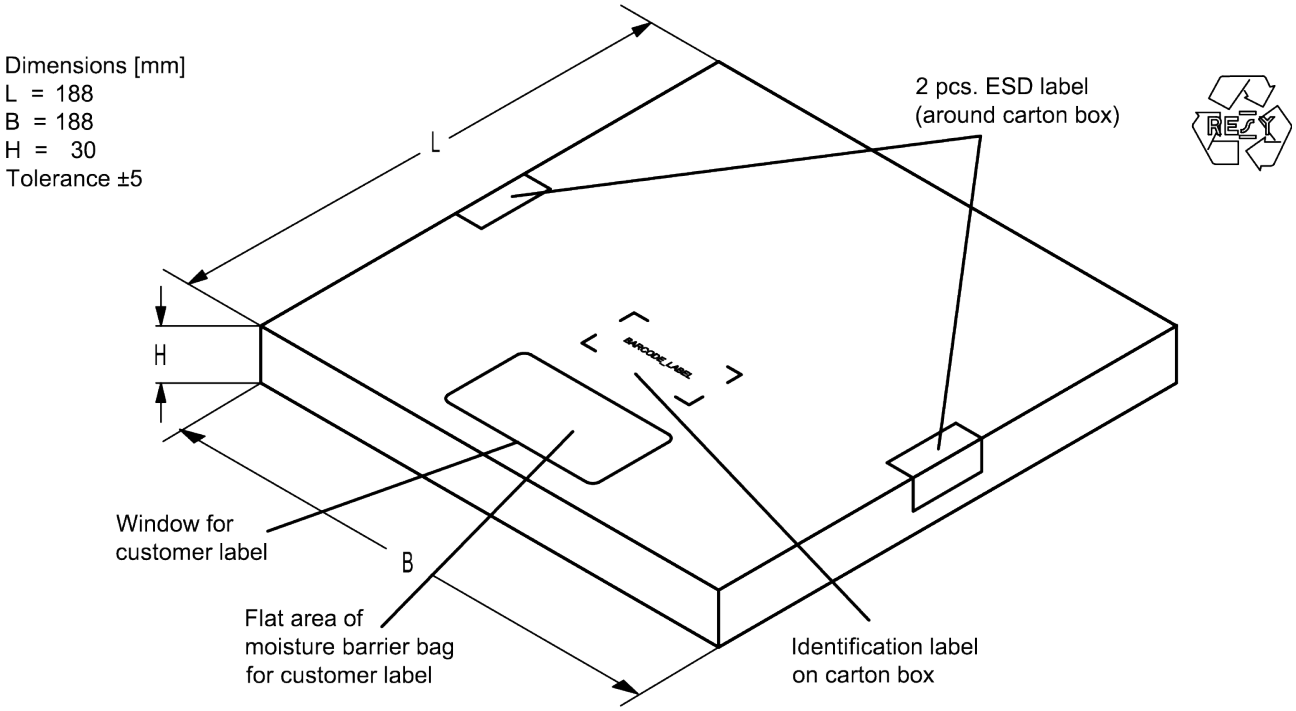

Figure 14: Drawing of folding box for reel with diameter of 180 mm.

11.3 Reel with diameter of 330 mm

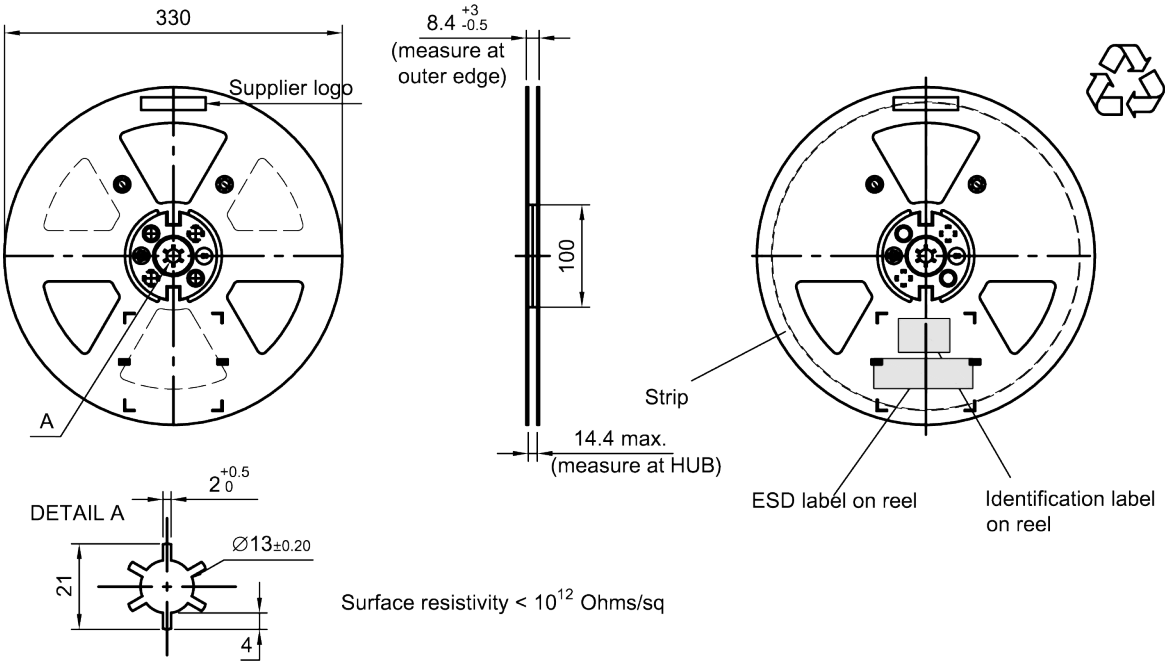

Figure 15: Drawing of reel (first-angle projection) with diameter of 330 mm.

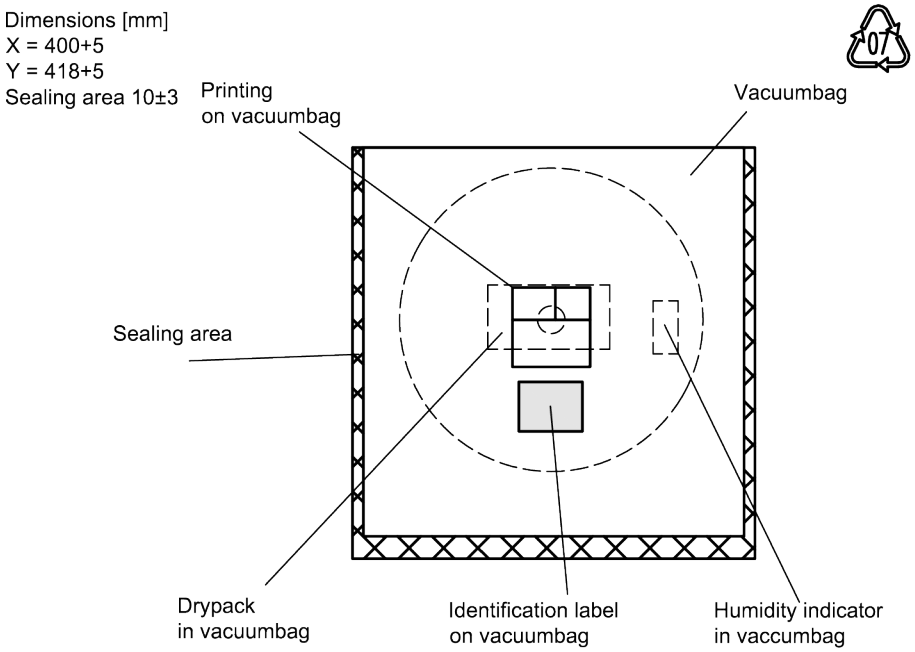

Figure 16: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

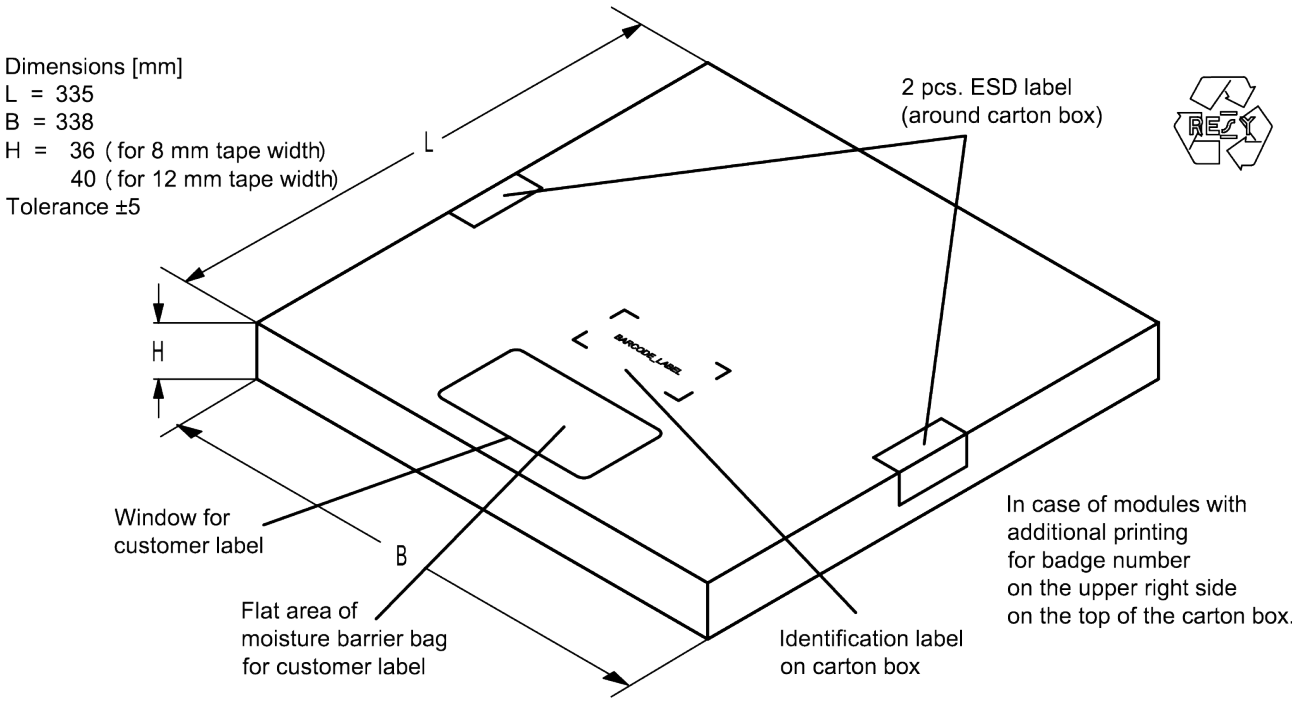

Figure 17: Drawing of folding box for reel with diameter of 330 mm.

12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

- Type number:

  The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
  is encoded by a special BASE32 code into a 3 digit marking.

  Example of decoding type number marking on device in decimal code.
  16J **=>** **1234**
  1 x 32^2 + **6** x 32^1 + **18 (=J)** x 32^0 **=** **1234**
  The BASE32 code for product type B1237 is 16N.

- Lot number:

  The last 5 digits of the lot number, e.g., **12345**,
  are encoded based on a special BASE47 code into a 3 digit marking.

  Example of decoding lot number marking on device in decimal code.
  5UY **=>** **12345**
  5 x 47^2 + **27 (=U)** x 47^1 + **31 (=Y)** x 47^0 **=** **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

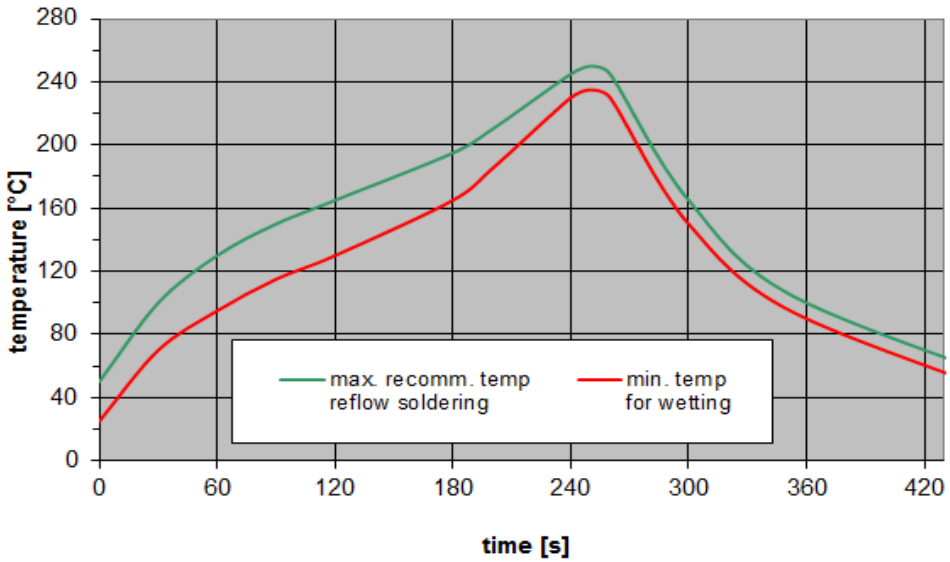

Figure 18: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog http://www.tdk.co.jp/tefe02/coil.htm#aname1 and Data Library for circuit simulation http://www.tdk.co.jp/etvcl/index.htm.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

16 Revision history

Changes compared to previously issued iteration.

Version	Originator	Detailed specification changes	Date
1.0	G. Bourjade	Initial preliminary datasheet.	Apr 03, 2018
1.1	G. Bourjade	Detailed Rx and Tx wideband rejection.	Apr 20, 2018

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.
   The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.